

# FDFS2P103A

## Integrated P-Channel PowerTrench® MOSFET and Schottky Diode

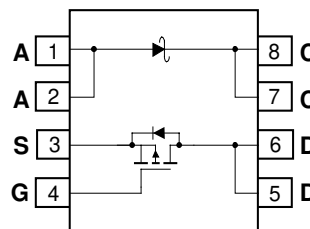
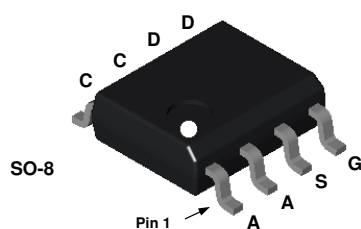
### General Description

The FDFS2P103A combines the exceptional performance of Fairchild's PowerTrench MOSFET technology with a very low forward voltage drop Schottky barrier rectifier in an SO-8 package.

This device is designed specifically as a single package solution for DC to DC converters. It features a fast switching, low gate charge MOSFET with very low on-state resistance. The independently connected Schottky diode allows its use in a variety of DC/DC converter topologies.

### Features

- -5.3 A, -30V  $R_{DS(ON)} = 59 \text{ m}\Omega @ V_{GS} = -10 \text{ V}$   
 $R_{DS(ON)} = 92 \text{ m}\Omega @ V_{GS} = -4.5 \text{ V}$
- $V_F < 0.35 \text{ V @ 1 A (} T_J = 125^\circ\text{C)}$   
 $V_F < 0.25 \text{ V @ 1 A (} T_J = 25^\circ\text{C)}$
- Schottky and MOSFET incorporated into single power surface mount SO-8 package
- Electrically independent Schottky and MOSFET pinout for design flexibility



### Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V <sub>DSS</sub>	MOSFET Drain-Source Voltage	-30	V
V <sub>GSS</sub>	MOSFET Gate-Source Voltage	±25	V
I <sub>D</sub>	Drain Current – Continuous (Note 1a)	-5.3	A
	– Pulsed	-20	
P <sub>D</sub>	Power Dissipation for Dual Operation	2	W
	Power Dissipation for Single Operation (Note 1a)	1.6	
	(Note 1b)	1	
	(Note 1c)	0.9	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C
V <sub>RRM</sub>	Schottky Repetitive Peak Reverse Voltage	30	V
I <sub>O</sub>	Schottky Average Forward Current (Note 1a)	1	A

### Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDFS2P103A	FDFS2P103A	13"	12mm	2500 units

### Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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#### Off Characteristics

$BV_{DSS}$	Drain–Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$		-22		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = -24\text{ V}, V_{GS} = 0\text{ V}$			-1	$\mu\text{A}$
$I_{GSS}$	Gate–Body Leakage	$V_{GS} = \pm 25\text{ V}, V_{DS} = 0\text{ V}$			$\pm 100$	nA

#### On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-1	-1.8	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$		4.2		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = -10\text{ V}, I_D = -5.3\text{ A}$ $V_{GS} = -4.5\text{ V}, I_D = -4\text{ A}$ $V_{GS} = -10\text{ V}, I_D = -5.3\text{ A}, T_J = 125^\circ\text{C}$		50 76 68	59 92 88	m $\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = -5\text{ V}, I_D = -5.3\text{ A}$		8.9		S

#### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = -15\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		535		pF
$C_{oss}$	Output Capacitance			135		pF
$C_{riss}$	Reverse Transfer Capacitance			75		pF
$R_G$	Gate Resistance		$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$		4.7	

#### Switching Characteristics (Note 2)

$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = -15\text{ V}, I_D = -1\text{ A},$ $V_{GS} = -10\text{ V}, R_{GEN} = 6\ \Omega$		11	21	ns
$t_r$	Turn–On Rise Time			16	28	ns
$t_{d(off)}$	Turn–Off Delay Time			15	26	ns
$t_f$	Turn–Off Fall Time			10	19	ns
$Q_g$	Total Gate Charge			5.7	8	nC
$Q_{gs}$	Gate–Source Charge	$V_{DS} = -15\text{ V}, I_D = -5.3\text{ A},$ $V_{GS} = -5\text{ V}$		1.8		nC
$Q_{gd}$	Gate–Drain Charge			2.4		nC

#### Drain–Source Diode Characteristics and Maximum Ratings

$I_S$	Maximum Continuous Drain–Source Diode Forward Current				-1.3	A
$V_{SD}$	Drain–Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -1.3\text{ A}$ (Note 2)		-0.8	-1.2	V

#### Schottky Diode Characteristics

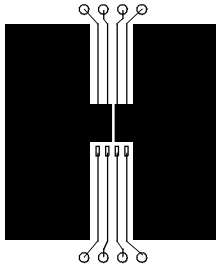
$I_R$	Reverse Leakage	$V_R = 30\text{ V}$			160	500	$\mu\text{A}$
$V_F$	Forward Voltage	$I_F = 0.1\text{ A}$	$T_J = 25^\circ\text{C}$		225	280	mV
			$T_J = 125^\circ\text{C}$		80	250	mV
		$I_F = 1\text{ A}$	$T_J = 25^\circ\text{C}$		305	350	mV
			$T_J = 125^\circ\text{C}$		185	250	mV
		$I_F = 3\text{ A}$	$T_J = 25^\circ\text{C}$		380	420	mV

## Thermal Characteristics

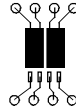
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1c)	135	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	40	$^{\circ}\text{C}/\text{W}$

**Notes:**

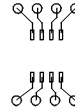
1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a) 78 $^{\circ}\text{C}/\text{W}$  when mounted on a 0.5in<sup>2</sup> pad of 2 oz copper



b) 125 $^{\circ}\text{C}/\text{W}$  when mounted on a 0.02 in<sup>2</sup> pad of 2 oz copper

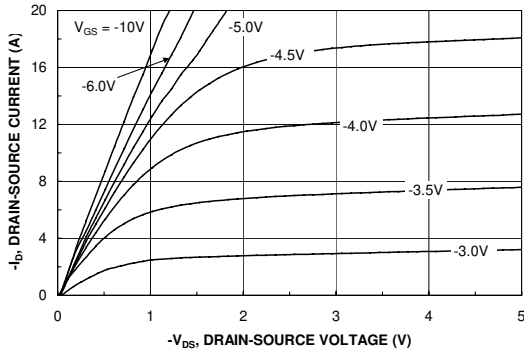


c) 135 $^{\circ}\text{C}/\text{W}$  when mounted on a minimum pad.

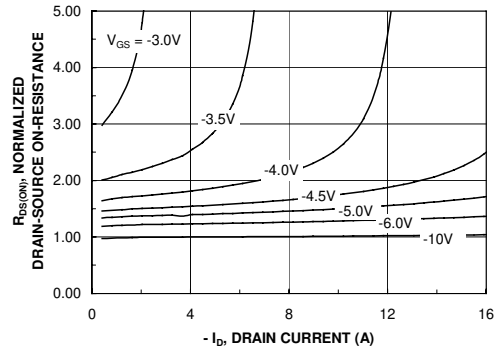
Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300 $\mu\text{s}$ , Duty Cycle < 2.0%

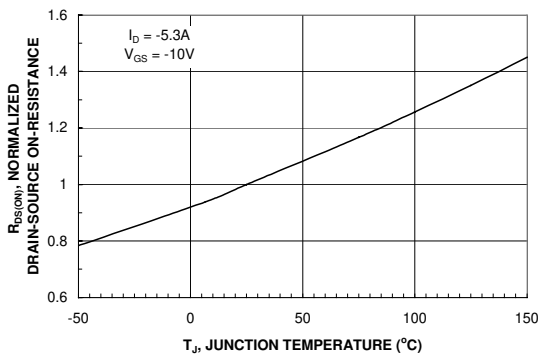
## Typical Characteristics



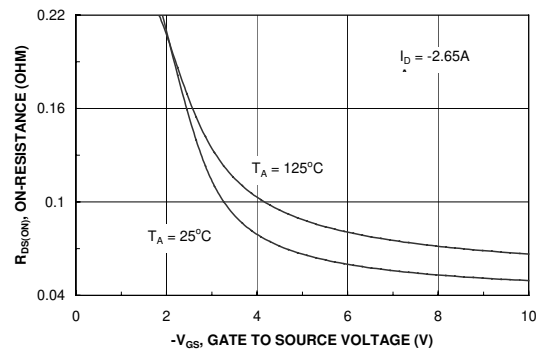
**Figure 1. On-Region Characteristics.**



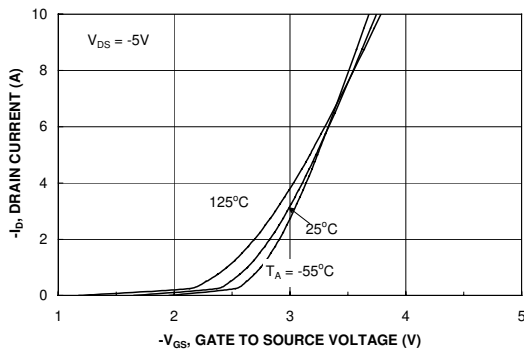
**Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.**



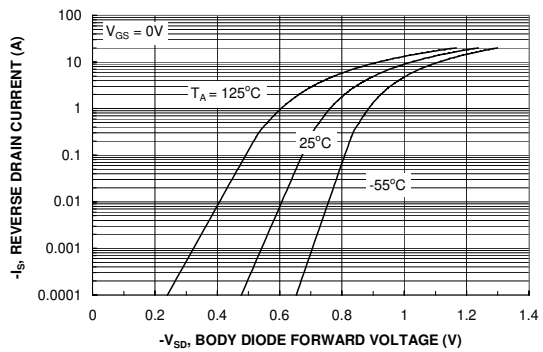
**Figure 3. On-Resistance Variation with Temperature.**



**Figure 4. On-Resistance Variation with Gate-to-Source Voltage.**



**Figure 5. Transfer Characteristics.**



**Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.**

## Typical Characteristics

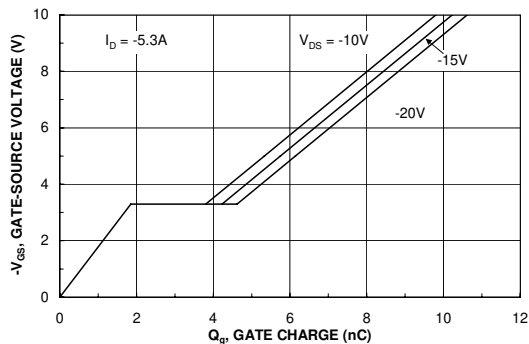


Figure 7. Gate Charge Characteristics.

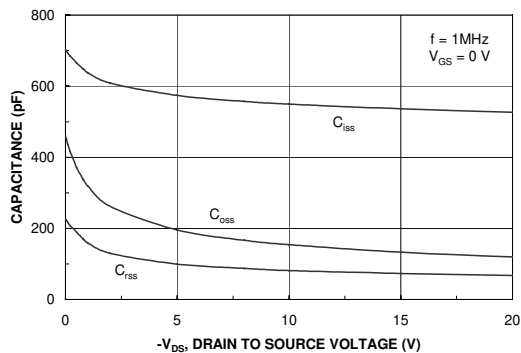


Figure 8. Capacitance Characteristics.

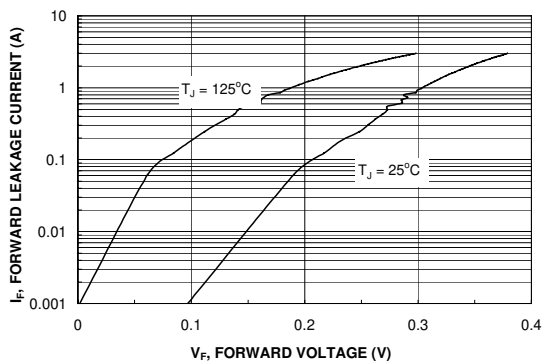


Figure 9. Schottky Diode Forward Voltage.

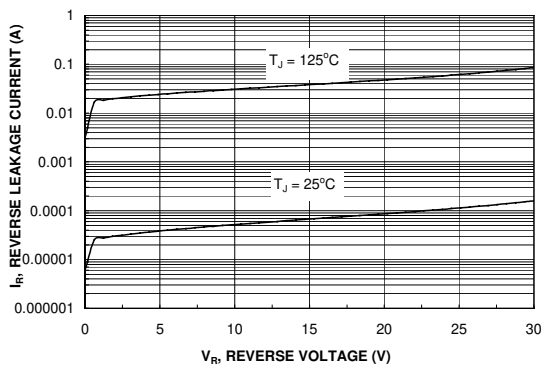


Figure 10. Schottky Diode Reverse Current.

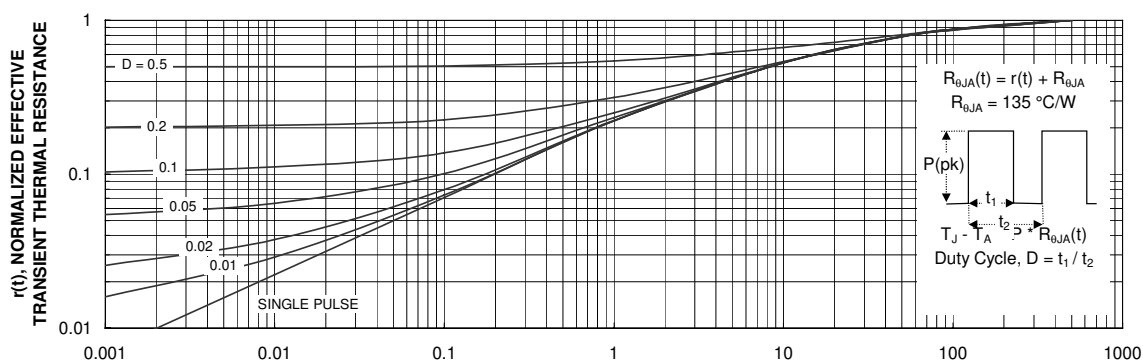


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.  
 Transient thermal response will change depending on the circuit board design.

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